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Kingbright WP914GT

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2x3mm RECTANGULAR SOLID LAMP

Part Number: WP914GT

Green

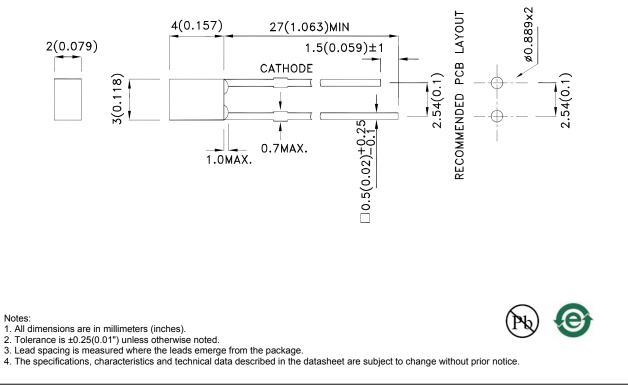
Features

- Low power consumption.
- Reliable and rugged.
- Excellent uniformity of light output.
- Suitable for level indicator.
- RoHS compliant.

Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



SPEC NO: DSAE9436



Selection Guide

Part No.	Part No. Dice Lens Type		lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP914GT	Green (GaP)	Green Transparent	3	8	90°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	568		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	I⊧=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.2	2.5	V	I⊧=20mA
IR	Reverse Current	Green		10	uA	VR = 5V

Notes:

 Wavelength: +/-1nm.
Forward Voltage: +/-0.1V.
Wavelength value is traceable to the CIE127-2007 compliant national standards.
Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

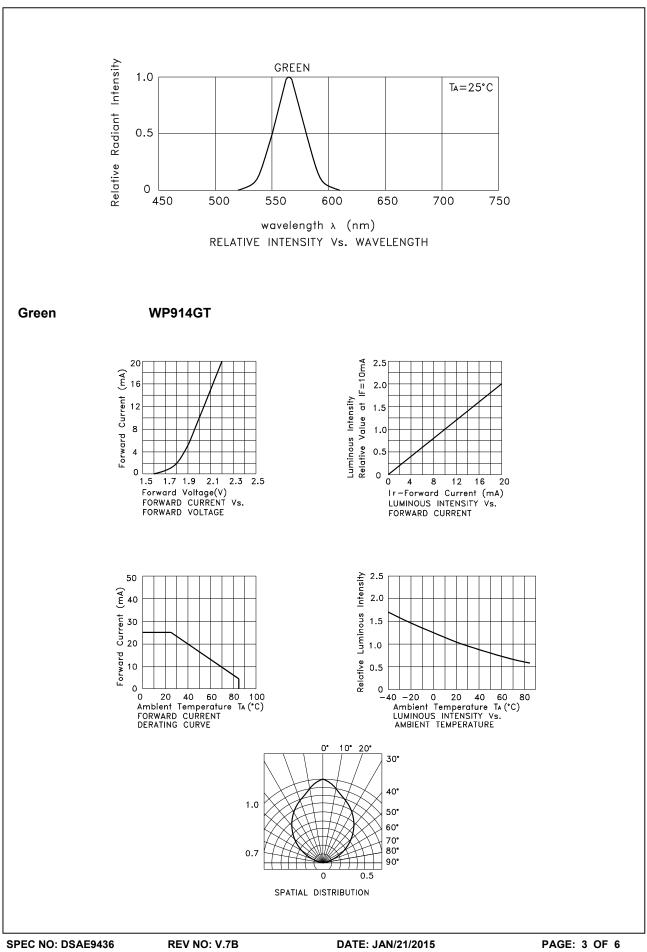
Parameter	Green	Units	
Power dissipation	62.5	mW	
DC Forward Current	25		
Peak Forward Current [1]	140	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Absolute Maximum Ratings at TA=25°C

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.
3. 5mm below package base.

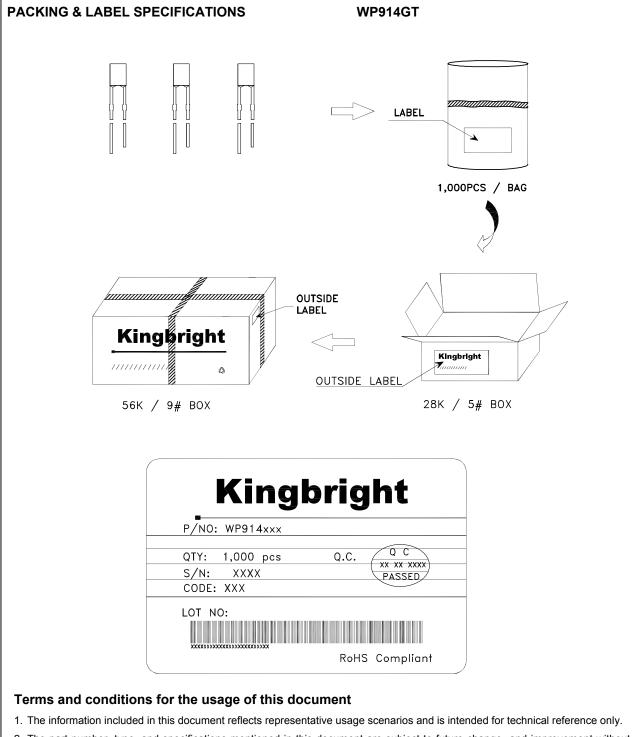






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- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
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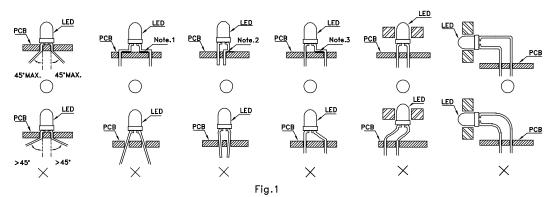
PEC NO: DSAE9436	REV NO: V.7B	DATE: JAN/21/2015



PRECAUTIONS

1. Storage conditions:

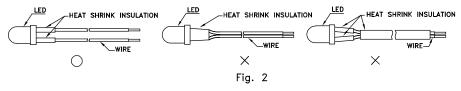
- a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- b.LEDs should be stored with temperature \leq 30°C and relative humidity < 60%.
- c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



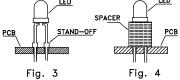
" \bigcirc " Correct mounting method "imes" Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure. (Fig. 2)



4. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 5. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 6. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



